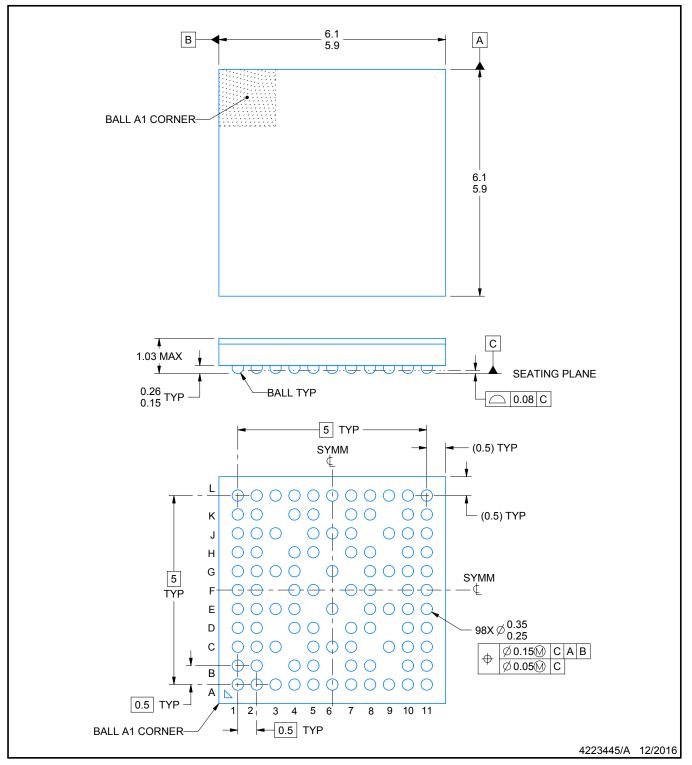
ABM0098A



PACKAGE OUTLINE

FCBGA - 1.03 mm max height

PLASTIC BALL GRID ARRAY



NOTES:



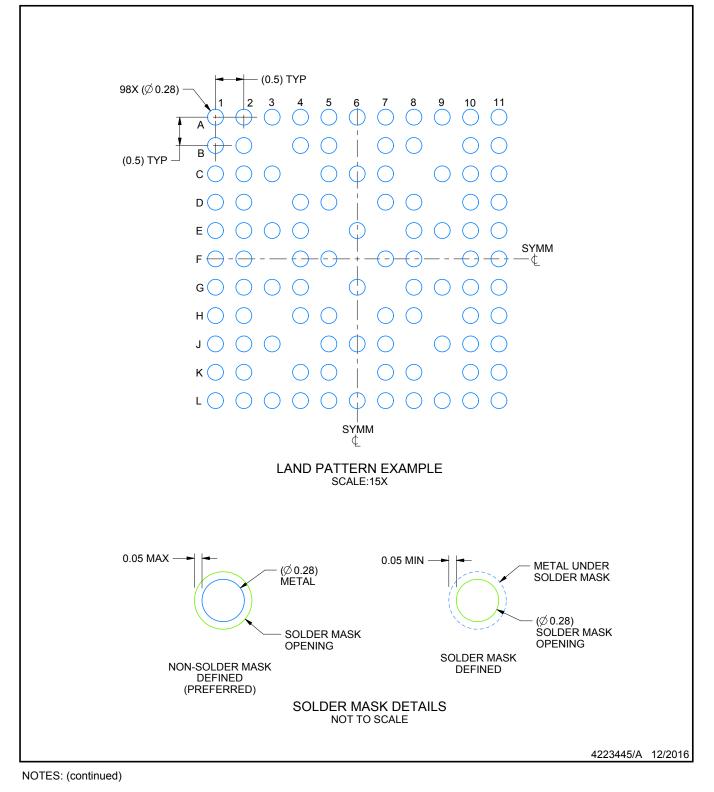
^{1.} All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.

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EXAMPLE BOARD LAYOUT

FCBGA - 1.03 mm max height

PLASTIC BALL GRID ARRAY



3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).

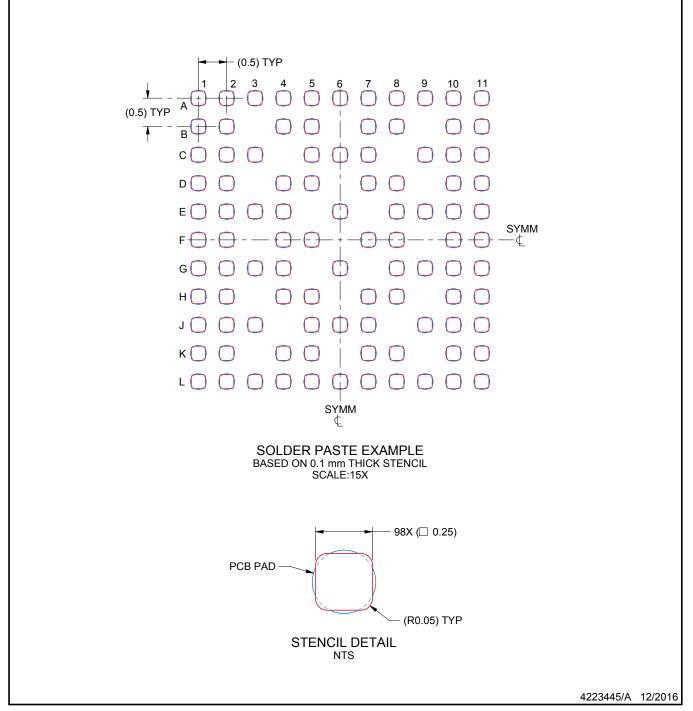


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EXAMPLE STENCIL DESIGN

FCBGA - 1.03 mm max height

PLASTIC BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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